

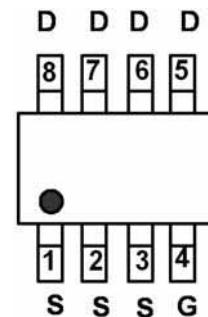
## 30V(D-S) N-Channel Enhancement Mode Power MOS FET

**General Features**

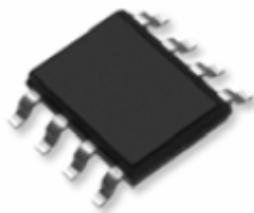
- $V_{DS} = 30V, I_D = 10A$
- $R_{DS(ON)} < 12m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 16m\Omega @ V_{GS}=4.5V$
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current

**Lead Free****Application**

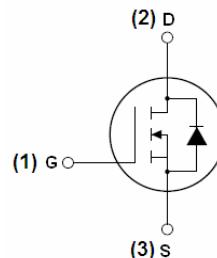
- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

**PIN Configuration**

Marking and pin assignment



SOP-8 top view



Schematic diagram

**Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MSN0310W	MSN0310W	SOP-8	Ø330mm	12mm	2500 units

**Absolute Maximum Ratings ( $T_A=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	10	A
Drain Current-Continuous( $T_C=100^\circ C$ )	$I_D (100^\circ C)$	6	A
Pulsed Drain Current	$I_{DM}$	50	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

**Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{eJC}$	50	°C/W
--	-----------	----	------

**Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**

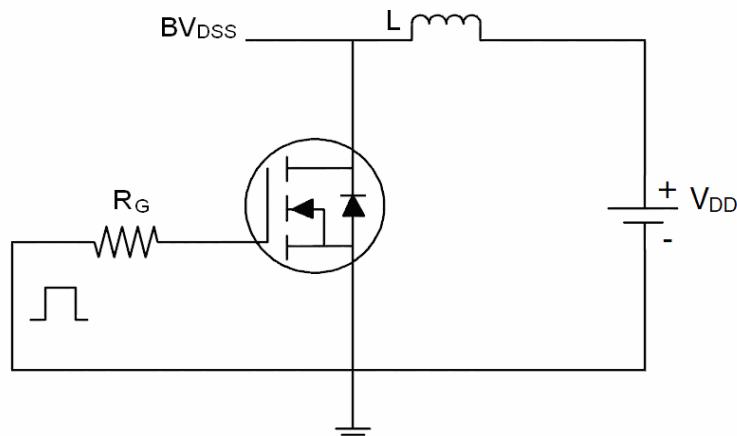
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	33	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	3	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	-	8	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=5\text{A}$	-	11	16	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$	15	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	1550	-	PF
Output Capacitance	$C_{\text{oss}}$		-	300	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	180	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=25\text{V}, I_{\text{D}}=1\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=6\Omega$	-	30	-	nS
Turn-on Rise Time	$t_r$		-	20	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	100	-	nS
Turn-Off Fall Time	$t_f$		-	80	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=5\text{V}$	-	13	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	5.5	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	3.5	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=10\text{A}$	-	-	1.2	V
Diode Forward Current	$I_{\text{s}}$		-	-	10	A

**Notes:**

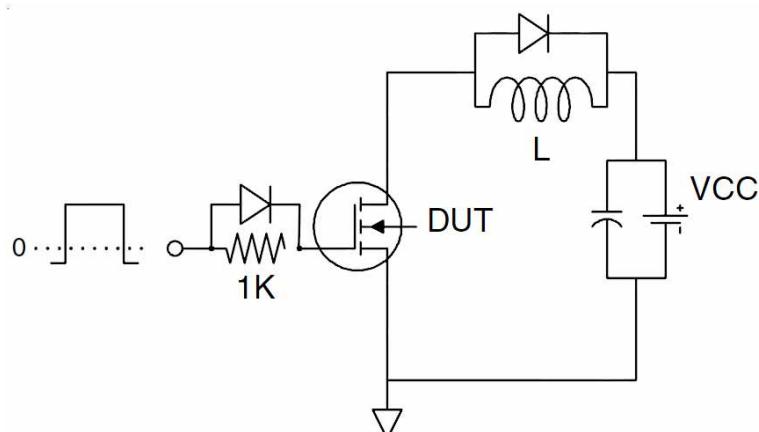
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Test Circuit

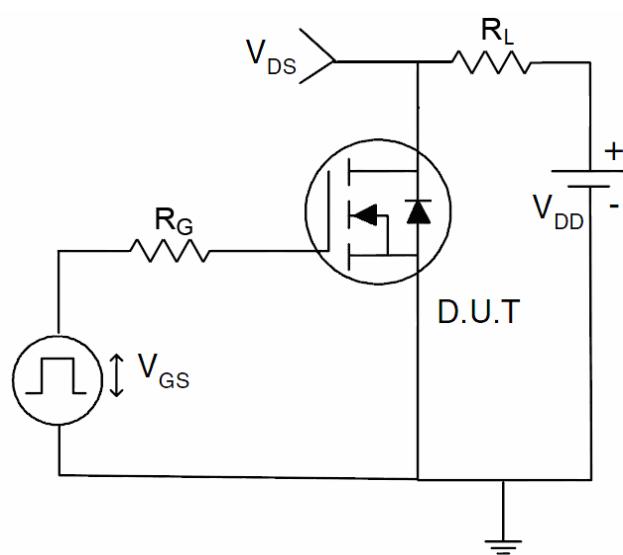
### 1) E<sub>AS</sub> Test Circuits

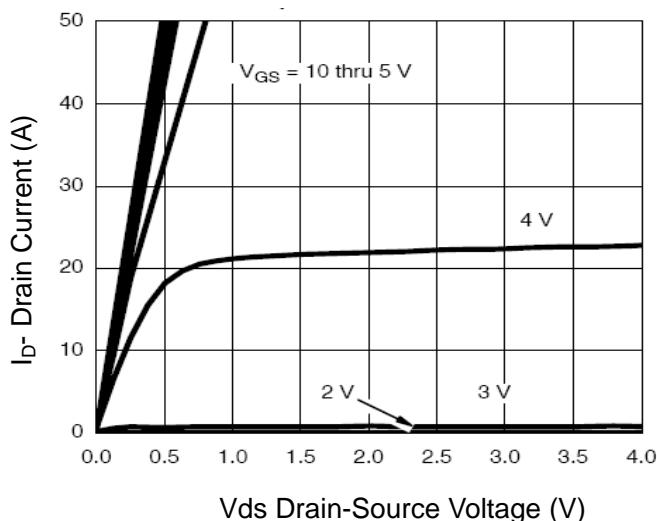
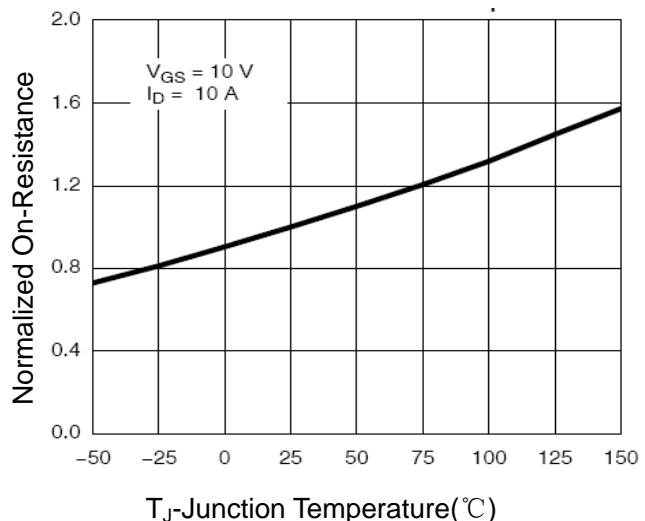
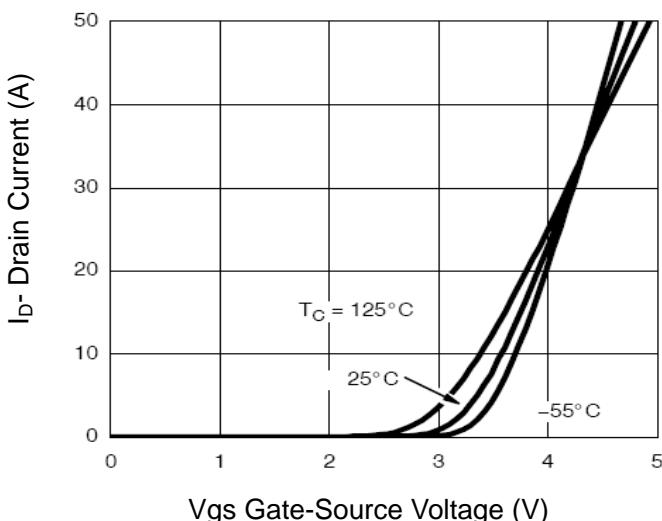
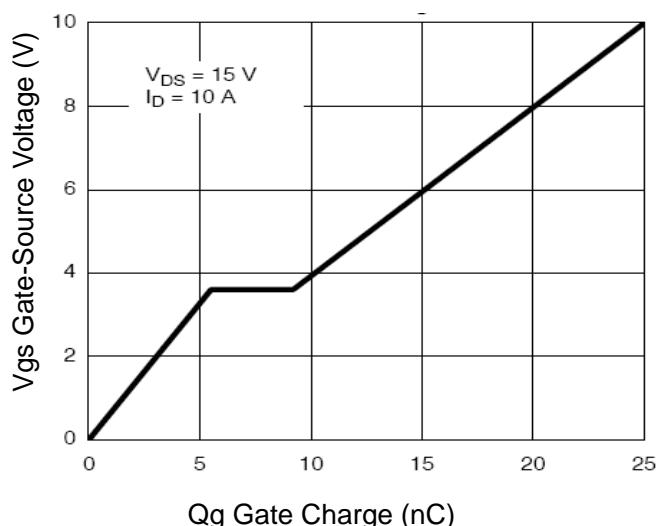
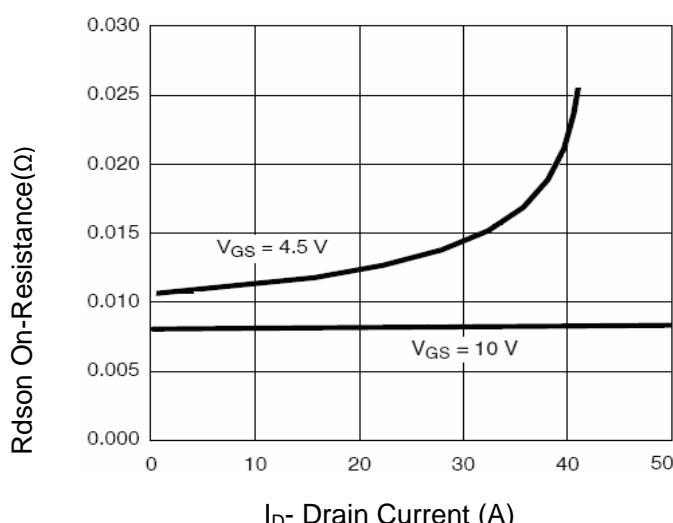
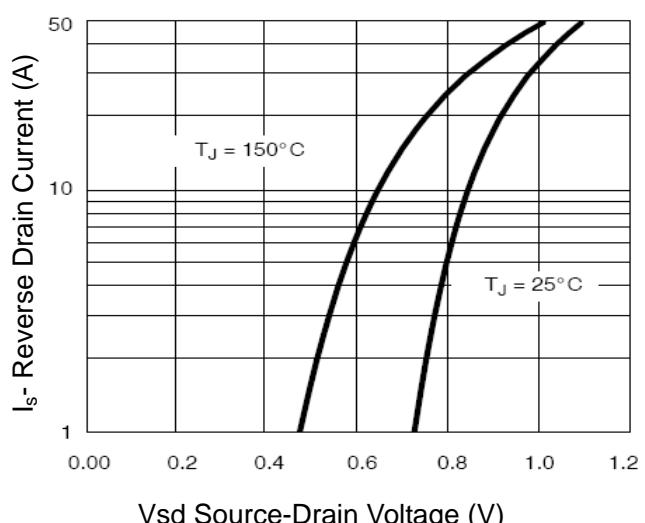


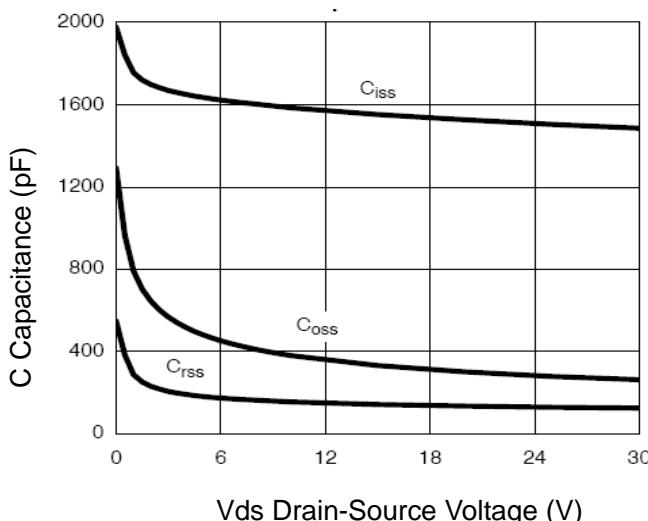
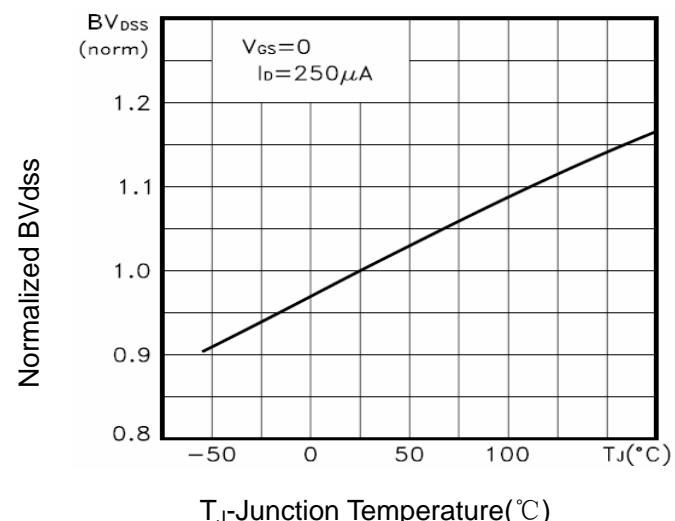
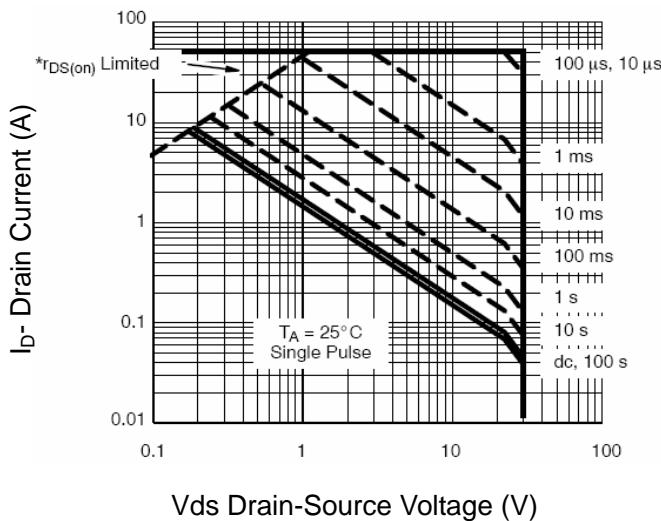
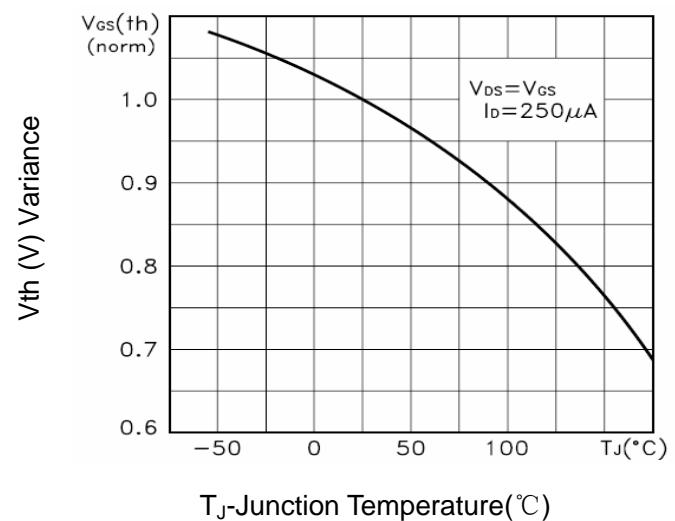
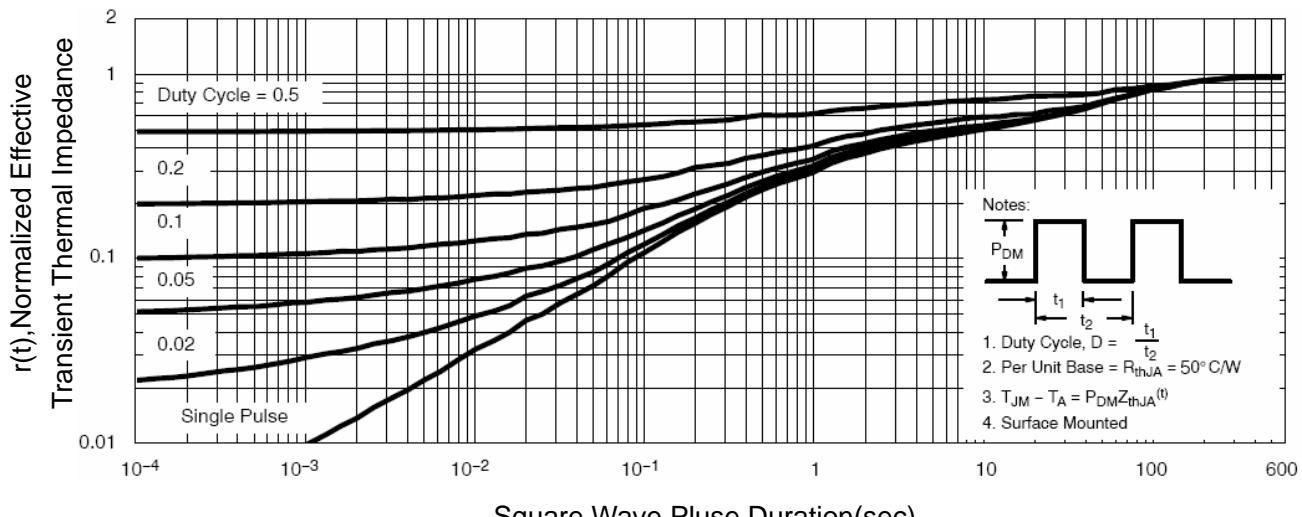
### 2) Gate Charge Test Circuit:



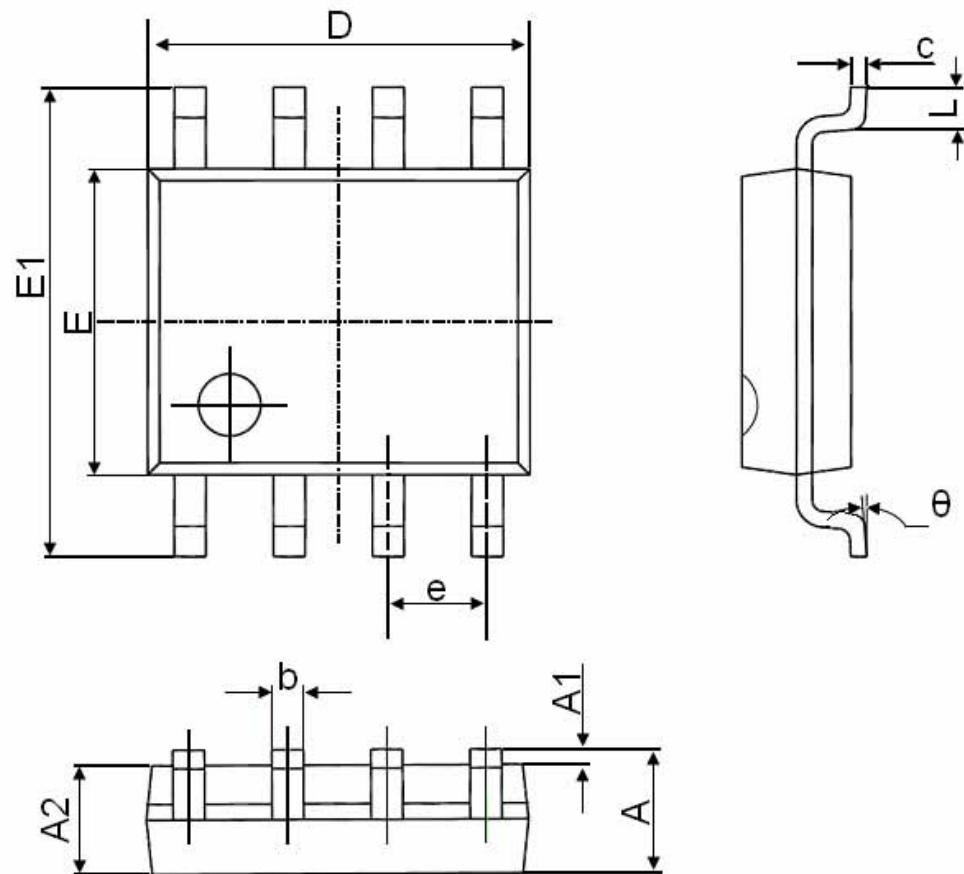
### 3) Switch Time Test Circuit:



**Typical Electrical and Thermal Characteristics (Curves)****Figure 1 Output Characteristics****Figure 4 Rdson-JunctionTemperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drain Diode Forward**

**Figure 7 Capacitance vs Vds****Figure 9  $BV_{dss}$  vs Junction Temperature****Figure 8 Safe Operation Area****Figure 10  $V_{gs(th)}$  vs Junction Temperature****Figure 11 Normalized Maximum Transient Thermal Impedance**

## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°